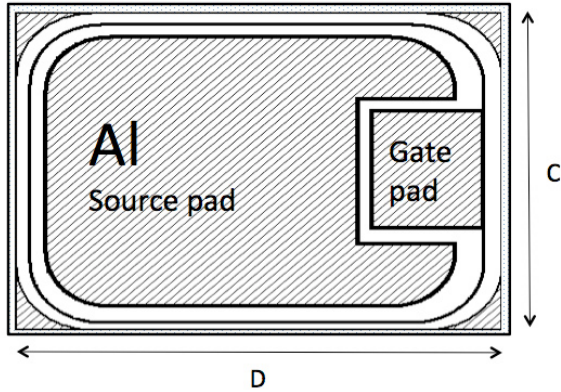
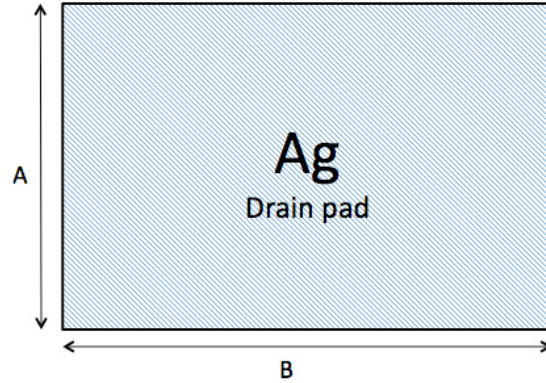


## Chip Features

### Front side



### Back side



Chip Size (um)	Thickness (um)	Pad Size-Gate (um)	Pad Size-Source (um)
3,480 * 2,680	350	430 * 550	1,000 * 2,000

## Referenced PKG Electrical Ratings TC = 25°C unless otherwise noted

### Characteristics (Tc=25°C, unless otherwise specified)

Symbol	Test Conditions	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>					
BVDSS	VGS=0, ID=250μA	500	-	-	V
ΔBVDSS/ΔTj	Reference to 25°C, ID=250μA		0.60		
IDSS	VDS =500V, VGS =0V	-	-	1	uA
	VDS =400V, VGS =0, Tj=125°C	-	-	10	
IGSSF	VGS =30V, VDS =0V	-	-	100	nA
IGSSR	VGS =-30V, VDS =0V	-	-	-100	nA
VGS	VDS = VGS, ID=250μA	2.0	-	4.0	V
*RDS(ON)	VGS =10V, ID =2.5A	-	1	1.4	mΩ